

67,200-327  
Serial Number 09/885,784



## AMENDMENT AND RESPONSE TO OFFICE ACTION

**TO:** COMMISSIONER OF PATENTS AND TRADEMARKS  
Washington, D.C. 20231

**FROM:** Tung & Associates  
838 West Long Lake Road - Suite 120  
Bloomfield Hills, MI 48302

**DATE:** 21 October 2002

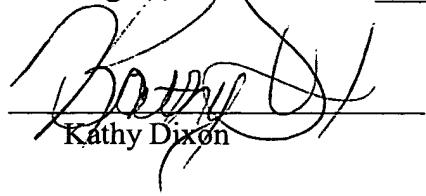
**REF:** APPLICANT : Liang  
SERIAL NO. : 09/885,784  
ART UNIT : 2823  
FILING DATE : 20 June 2001  
ATT'Y NO. : 67,200-327  
EXAMINER : Julio J. Maldonado  
TITLE : Laminating Method for Forming Integrated Circuit  
Microelectronic Fabrication

*NO TEL possible  
NO fax  
3/19/03*  
Sir:

In response to an office communication mailed on 30 August 2002, please  
consider the following amendments and remarks pertaining to the above referenced application.

## CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with sufficient postage  
as first class mail in an envelope addressed to the Assistant Commissioner for Patents,  
Washington, D.C. 20231 on 11/1 2002.

  
\_\_\_\_\_  
Kathy Dixon

11/1/02  
\_\_\_\_\_  
Date

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